

## **CONDUCTIVE MATERIAL COMPOSITIONS, APPARATUS, SYSTEMS, AND METHODS**

### **Abstract of the Disclosure**

Various apparatus and systems, as well as methods and articles, may include the use of several compositions, such as solder formulations, including about 78%-83% by weight of lead, about 9%-11% by weight of antimony, about 1%-3% by weight of silver, and a balance of tin. Some embodiments include a process of removing a previously-existing lead finish, and applying a new finish to the lead to improve solder operation compatibility, as well as solder joint reliability in high temperature environments.